

# M1MA141WKT1G, M1MA142WKT1G, SM1MA142WKT1G,



ON Semiconductor®

<http://onsemi.com>

## Common Cathode Silicon Dual Switching Diode

This Common Cathode Silicon Epitaxial Planar Dual Diode is designed for use in ultra high speed switching applications. This device is housed in the SC-70 package which is designed for low power surface mount applications.

### Features

- Fast  $t_{rr}$ , < 3.0 ns
- Low  $C_D$ , < 2.0 pF
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Value	Unit
Reverse Voltage M1MA141WKT1G M1MA142WKT1G, SM1MA142WKT1G	$V_R$	40 80	Vdc
Peak Reverse Voltage M1MA141WKT1G M1MA142WKT1G, SM1MA142WKT1G	$V_{RM}$	40 80	Vdc
Forward Current Single Dual	$I_F$	100 150	mAdc
Peak Forward Current Single Dual	$I_{FM}$	225 340	mAdc
Peak Forward Surge Current M1MA141WKT1G M1MA142WKT1G, SM1MA142WKT1G	$I_{FSM}$ (Note 1)	500 750	mAdc

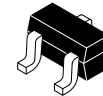
### THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	$P_D$	150	mW
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

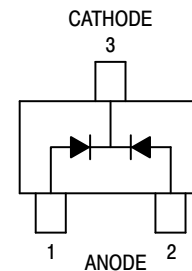
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1.  $t = 1 \text{ SEC}$

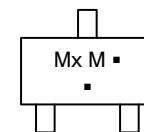
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SC-70 (SOT-323)  
CASE 419  
STYLE 5



### MARKING DIAGRAM



Mx = Device Code  
x = T for 141  
U for 142  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
M1MA141WKT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
M1MA142WKT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
SM1MA142WKT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# M1MA141WKT1G, M1MA142WKT1G, SM1MA142WKT1G,

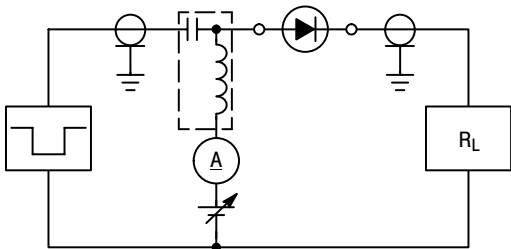
## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Characteristic	Condition	Symbol	Min	Max	Unit
Reverse Voltage Leakage Current M1MA141WKT1G M1MA142WKT1G, SM1MA142WKT1G	$V_R = 35\text{ V}$ $V_R = 75\text{ V}$	$I_R$	– –	0.1 0.1	$\mu\text{A}_{dc}$
Forward Voltage	$I_F = 100\text{ mA}$	$V_F$	–	1.2	Vdc
Reverse Breakdown Voltage M1MA141WKT1G M1MA142WKT1G, SM1MA142WKT1G	$I_R = 100\ \mu\text{A}$	$V_R$	40 80	– –	Vdc
Diode Capacitance	$V_R = 0, f = 1.0\text{ MHz}$	$C_D$	–	2.0	pF
Reverse Recovery Time (Figure 1)	$I_F = 10\text{ mA}, V_R = 6.0\text{ V},$ $R_L = 100\ \Omega, I_{rr} = 0.1 I_R$	$t_{rr}$ (Note 2)	–	3.0	ns

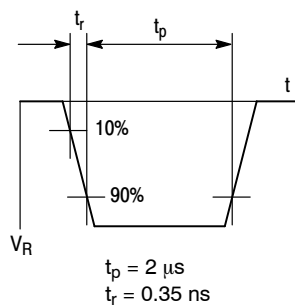
2.  $t_{rr}$  Test Circuit

M1MA141WKT1G, M1MA142WKT1G, SM1MA142WKT1G,

RECOVERY TIME EQUIVALENT TEST CIRCUIT



INPUT PULSE



OUTPUT PULSE

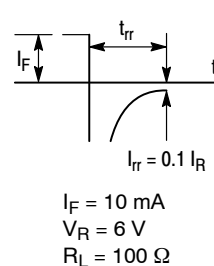


Figure 1. Recovery Time Equivalent Test Circuit

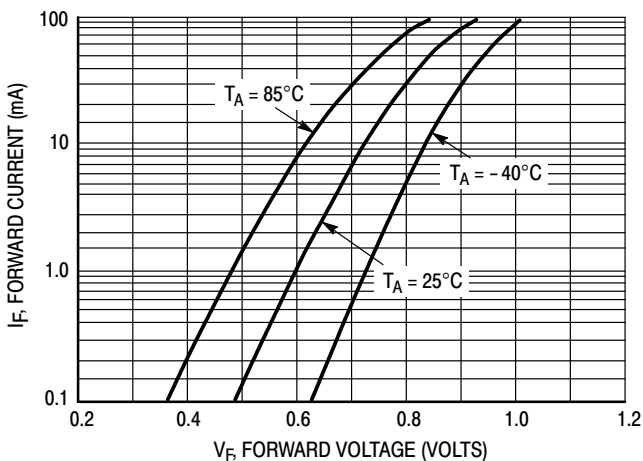


Figure 2. Forward Voltage

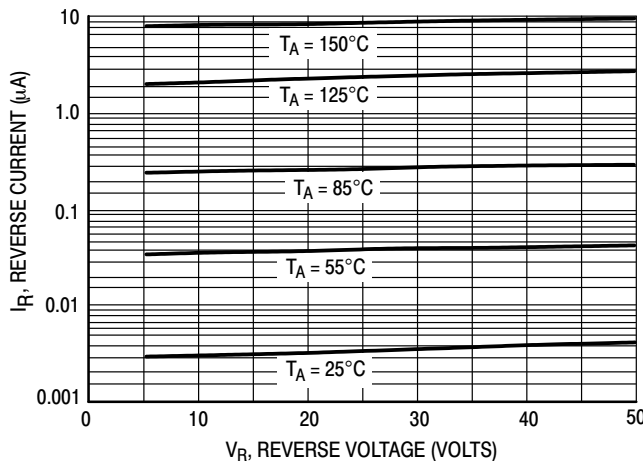


Figure 3. Reverse Current

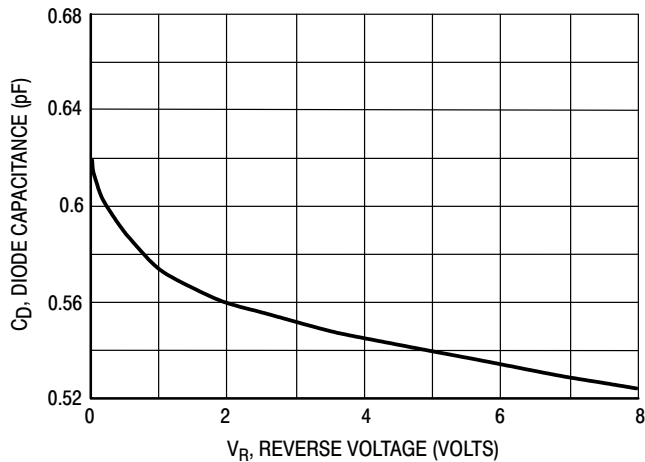
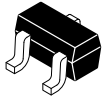


Figure 4. Diode Capacitance

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

## SC-70 (SOT-323) CASE 419 ISSUE R

DATE 11 OCT 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

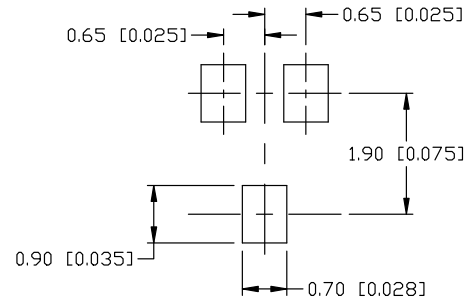
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
H <sub>E</sub>	2.00	2.10	2.40	0.079	0.083	0.095

### GENERIC MARKING DIAGRAM



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

### SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE
STYLE 6: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 7: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 8: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 9: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. ANODE-CATHODE
				STYLE 11: PIN 1. CATHODE 2. CATHODE 3. CATHODE

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